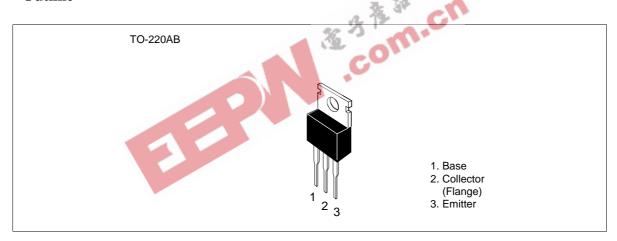
Silicon NPN Triple Diffused

HITACHI

Application

High voltage power amplifier

Outline



Absolute Maximum Ratings (Ta = 25°C)

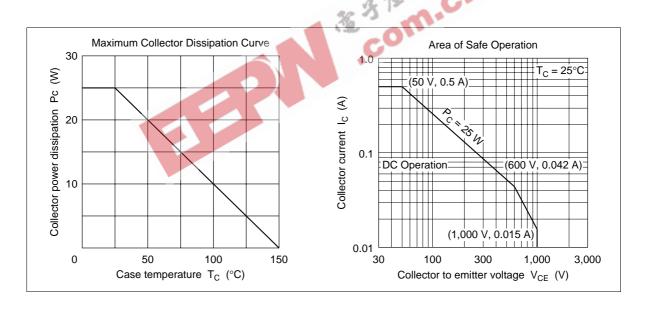
| Item | Symbol | Rating | Unit |
|------------------------------|-------------------|-------------|------|
| Collector to base voltage | V_{CBO} | 1000 | V |
| Collector to emitter voltage | V _{CEO} | 1000 | V |
| Emitter to base voltage | V_{EBO} | 5 | V |
| Collector current | I _c | 0.5 | A |
| Collector power dissipation | P _c | 1.8 | W |
| | P _c *1 | 25 | W |
| Junction temperature | Tj | 150 | °C |
| Storage temperature | Tstg | -55 to +150 | °C |

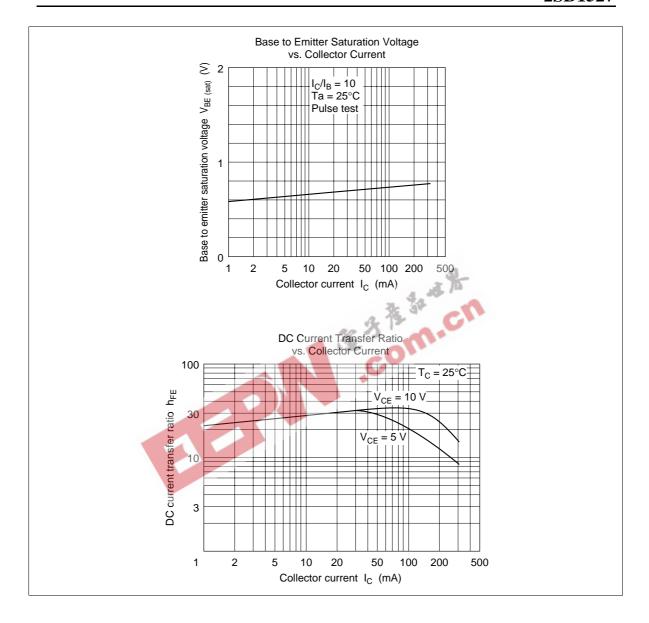
Note: 1. Value at $T_c = 25^{\circ}C$.

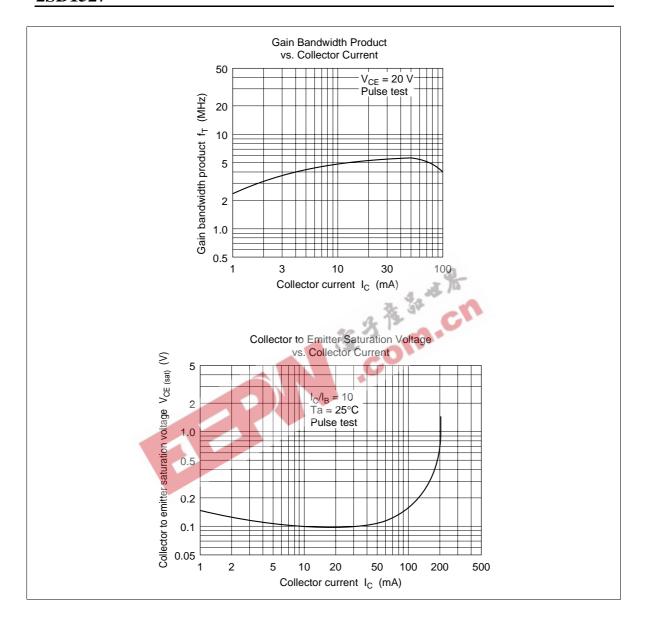


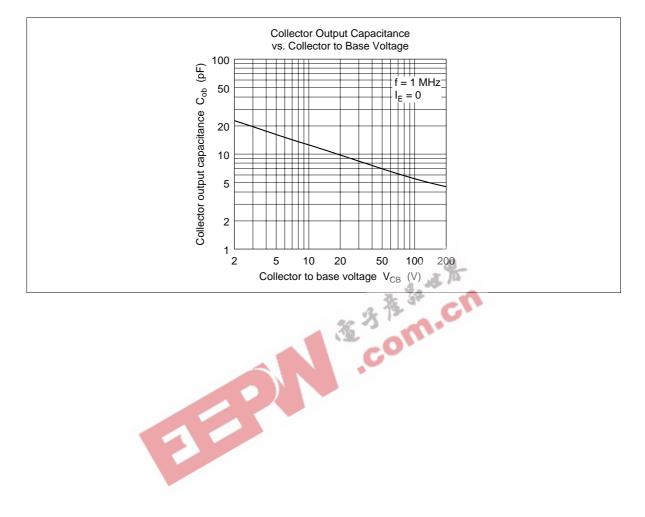
Electrical Characteristics (Ta = 25°C)

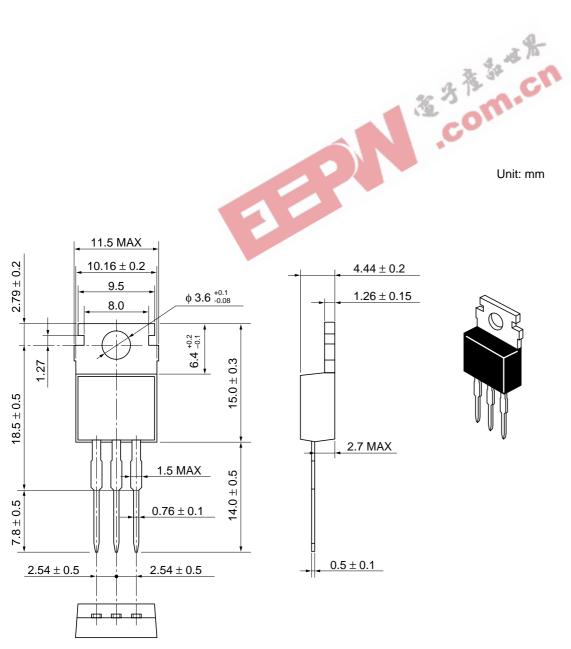
| Item | Symbol | Min | Тур | Max | Unit | Test conditions |
|---|-----------------------|------|-----|------|------|---|
| Collector to emitter breakdown voltage | $V_{(BR)CEO}$ | 1000 | _ | _ | V | I_{C} = 1 mA, R_{BE} = ∞ |
| Emitter to base breakdown voltage | $V_{(BR)EBO}$ | 5 | _ | _ | V | $I_{E} = 1 \text{ mA}, I_{C} = 0$ |
| Collector cutoff current | I _{CBO} | _ | _ | 10 | μΑ | V _{CB} = 800 V, I _E = 0 |
| DC current transfer ratio | h _{FE1} | 10 | _ | _ | | $V_{CE} = 5 \text{ V}, I_{C} = 10 \text{ mA}$ |
| | h _{FE2} | 10 | _ | _ | | $V_{CE} = 5 \text{ V}, I_{C} = 100 \text{ mA}$ |
| Base to emitter voltage | V_{BE} | _ | _ | 1.2 | V | $V_{CE} = 5 \text{ V}, I_{C} = 100 \text{ mA}$ |
| Collector to emitter saturation voltage | $V_{\text{CE (sat)}}$ | _ | _ | 5 | V | $I_{\rm C} = 300 \text{ mA}, I_{\rm B} = 60 \text{ mA}$ |
| Gain bandwidth product | f⊤ | _ | 5 | _ | MHz | $V_{CE} = 20 \text{ V}, I_{C} = 50 \text{ mA}$ |
| Collector output capacitance | Cob | _ | 5 | - 25 | pF | $V_{CB} = 100 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$ |











| Hitachi Code | TO-220AB |
|--------------------------|----------|
| JEDEC | Conforms |
| EIAJ | Conforms |
| Weight (reference value) | 1 8 a |

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Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109 URI

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For further information write to:

Hitachi Semiconductor (America) Inc. 179 East Tasman Drive, San Jose,CA 95134 Tel: <1> (408) 433-1990 Fax: <1>(408) 433-0223 Hitachi Europe GmbH Electronic components Group Dornacher Stra§e 3 D-85622 Feldkirchen, Munich Germany Tel: <49> (89) 9 9180-0

Fax: <49> (89) 9 29 30 00 Hitachi Europe Ltd. Electronic Components Group.

Whitebrook Park

Lower Cookham Road

Maidenhead Berkshire SL6 8YA, United Kingdom Tel: <44> (1628) 585000 Fax: <44> (1628) 778322

Hitachi Asia Pte. Ltd. 16 Collyer Quay #20-00 Hitachi Tower Singapore 049318 Tel: 535-2100 Fax: 535-1533

Hitachi Asia Ltd

Taipei Branch Office 3F, Hung Kuo Building. No.167 Tun-Hwa North Road, Taipei (105) Tel: <886> (2) 2718-3666 Fax: <886> (2) 2718-8180

Hitachi Asia (Hong Kong) Ltd. Group III (Electronic Components) 7/F., North Tower, World Finance Centre, Harbour City, Canton Road, Tsim Sha Tsui, Kowloon, Hong Kong Tel: <852> (2) 735 9218 Fax: <852> (2) 730 0281 Telex: 40815 HITEC HX

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